

ABSTRACT OF THE DISCLOSURE

A circuit board having a dielectric substrate, a grounding surface formed on at least one surface of the dielectric substrate, and transmission lines formed on one surface of the dielectric substrate for transmitting electrical signals. At least a portion of each of the transmission lines is isolated from an upper surface of the dielectric substrate to reduce the effective permittivity between the transmission lines and the grounding surface and a dielectric loss therebetween. In a method of manufacturing a circuit board, first, a sacrificial layer is formed on a dielectric substrate. Next, supporter patterns and transmission line patterns are formed by patterning the sacrificial layer. Then, supporters and transmission lines are formed in the supporter patterns and transmission line patterns, respectively. Following this, the sacrificial layer is removed so that the transmission lines are isolated from the upper surface of the dielectric substrate. Thereafter, a grounding surface is formed on at least one surface of the dielectric substrate.